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Vishay Semiconductors

High Speed Infrared Emitting Diodes, 850 nm, **Surface Emitter Technology**



DESCRIPTION

As part of the SurfLightTM portfolio, the VSMY2853 series are infrared, 850 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- Automotive sensors
- Miniature light barrier
- Photointerrupters
- · Optical switch
- Emitter source for proximity sensors
- IR illumination

FEATURES

 Package type: surface-mount · Package form: GW, RGW



AEC-Q101 qualified

Peak wavelength: λ_p = 850 nm

· High reliability

· High radiant power

· Very high radiant intensity

• Angle of half intensity: $\varphi = \pm 28^{\circ}$

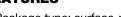
• Suitable for high pulse current operation

· Terminal configurations: gullwing or reverse gullwing

Package matches with detector VEMD2503X01 series

• Floor life: 4 weeks, MSL 2a, according to J-STD-020

· Material categorization: for definitions of compliance please see www.vishay.com/doc?99912











PRODUCT SUMMARY					
COMPONENT	I _e (mW/sr)	φ (deg)	$λ_{\mathbf{p}}$ (nm)	t _r (ns)	
VSMY2853RGX01	50	± 28	850	10	
VSMY2853GX01	50	± 28	850	10	

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMY2853RGX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing		
VSMY2853GX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing		

Note

MOQ: minimum order quantity



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ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_{R}	5	V
Forward current		I _F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I _{FM}	200	mA
Surge forward current	t _p = 100 μs	I _{FSM}	1	Α
Power dissipation		P _V	190	mW
Junction temperature		Tj	100	°C
Operating temperature range		T _{amb}	-40 to +85	°C
Storage temperature range		T _{stg}	-40 to +100	°C
Soldering temperature	According to Fig. 7, J-STD-020	T _{sd}	260	°C
Thermal resistance junction-to-ambient	EIA / JESD51	R _{thJA}	250	K/W

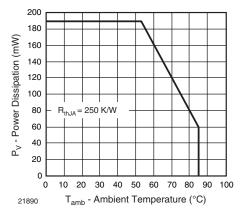


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

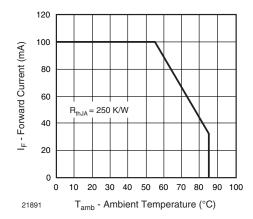


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Farmend valte no	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V _F	-	1.6	1.9	V
Forward voltage	$I_F = 1 \text{ A}, t_p = 100 \ \mu \text{s}$	V _F	-	2.8	-	V
Temperature coefficient of V _F	I _F = 100 mA	TK _{VF}	-	-1.5	-	mV/K
Reverse current		I _R	Not designed for reverse operation		μΑ	
Junction capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0 \text{ mW/cm}^2$	CJ	-	50	-	рF
Padient intensity	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	l _e	27	50	75	mW/sr
Radiant intensity	$I_F = 1 \text{ A}, t_p = 100 \ \mu \text{s}$	l _e	-	350	-	mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	фe	-	55	-	mW
Temperature coefficient of radiant power	I _F = 100 mA	TKφ _e	-	-0.12	-	%/K
Angle of half intensity		φ	-	± 28	-	deg
Peak wavelength	I _F = 100 mA	λ_{p}	840	850	870	nm
Spectral bandwidth	I _F = 100 mA	Δλ	-	30	-	nm
Temperature coefficient of λ _p	I _F = 100 mA	TKλ _p	-	0.25	-	nm/K
Rise time	I _F = 100 mA, 10 % to 90 %	t _r	-	10	-	ns
Fall time	I _F = 100 mA, 10 % to 90 %	t _f	-	10	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

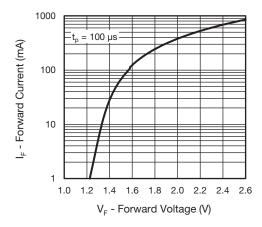


Fig. 3 - Forward Current vs. Forward Voltage

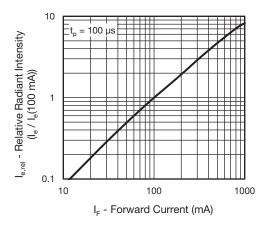


Fig. 4 - Relative Radiant vs. Forward Current

300 Max. 260 °C 250 245 °C ·240 °C 217 remperature (°C) 200 Max. 30 s 150 Max. 120 s Max. 100 s 100 Max. ramp down 6 °C/s Max. ramp up 3 °C/s 50 0 50 100 150 200 250 300 19841-1 Time (s)

SOLDER PROFILE

Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

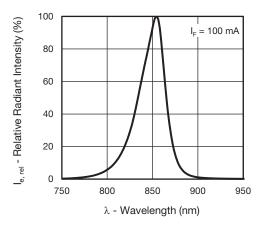


Fig. 5 - Relative Radiant Power vs. Wavelength

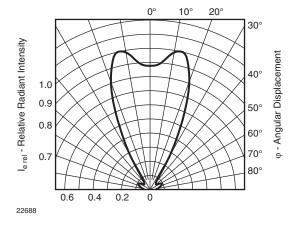


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

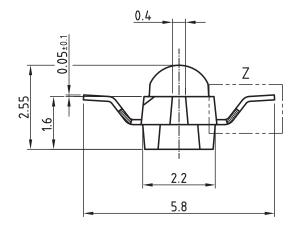
Conditions: T_{amb} < 30 °C, RH < 60 %

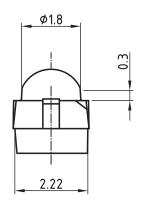
Moisture sensitivity level 2a, according to J-STD-020.

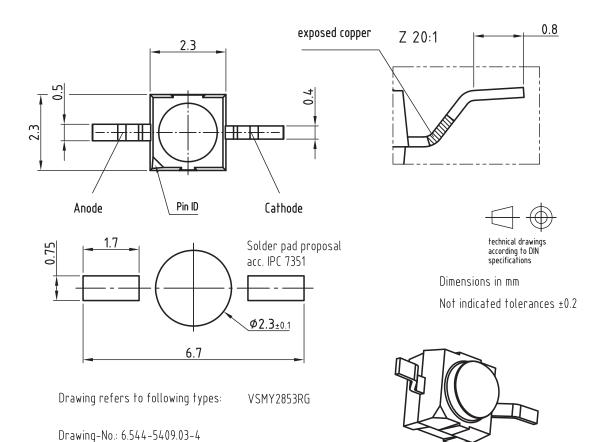
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.

PACKAGE DIMENSIONS in millimeters: VSMY2853RGX01

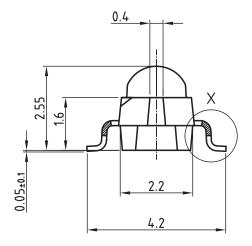


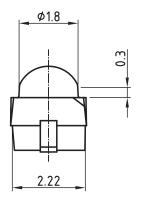


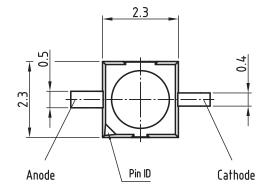


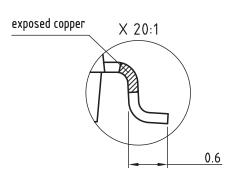
Issue: prel. 03.08.12

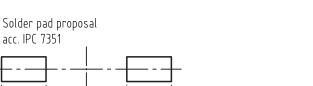
PACKAGE DIMENSIONS in millimeters: VSMY2853GX01













Drawing refers to following types: VSMY2853G

2.45 5.15

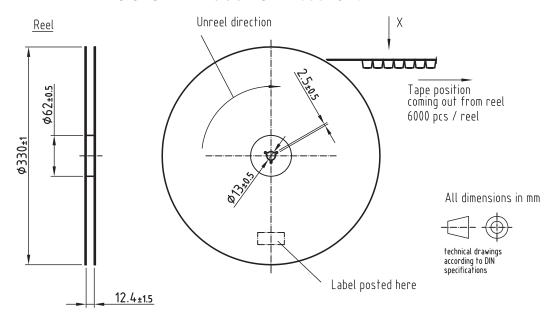
Dimensions in mm Not indicated tolerances ±0.2

Drawing-No.: 6.544-5408.03-4

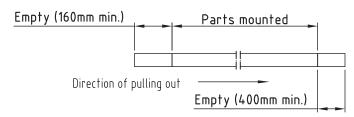
Issue: prel; 03.08.12



TAPING AND REEL DIMENSIONS in millimeters: VSMY2853RGX01

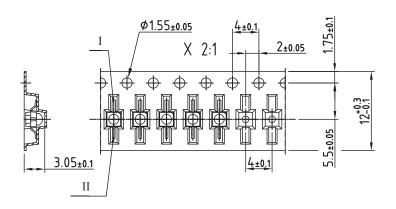


Leader and trailer tape:



Terminal position in tape

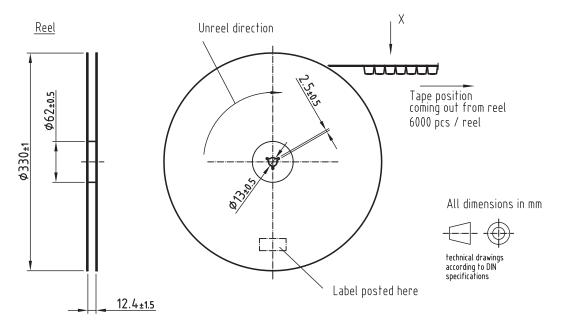
Device	Lead I	Lead II	
VSMB2943RGX01			
VSMF2893RGX01	Cathode	Anode	
VEMD2x03X01	Carnoue	Alloue	
VEMT2x03X01	Collector	Emitter	
	Collector	Lillitei	
VSMY2853RG	Anode	Cathode	



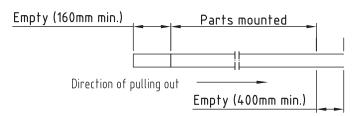
Drawing refers to following types: Reel dimensions and tape see table

Drawing-No.: 9.800-5100.02-4 Issue: prel; 03.08.12

TAPING AND REEL DIMENSIONS in millimeters: VSMY2853GX01

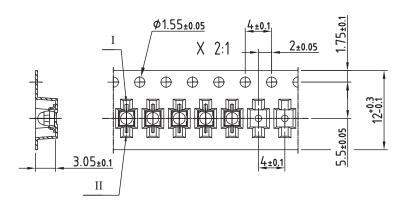


Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II
VSMB2943GX01		
VSMF2893GX01	Cathode	Anode
VEMD2x23X01	Carriode	Alloue
VEMT2x23X01	Collector	Emitter
	Collector	Ellitter
VSMY2853G	Anode	Cathode



Drawing refers to following types: see table

Reel dimensions and tape

Drawing-No.: 9.800-5091.21-4

Issue: prel; 03.08.12



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